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These assemblies are ESD precautions shall be observed. Z3 Assembly Note These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable. Z4 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.	с	PCB Label Size: 0.65" x 0.20 " ZZ1 Label Assembly Note This Assembly Note is for PCB labels only							
		These assemblies are ESD sensitive, ESD precaution ZZ3 Assembly Note These assemblies must be clean and free from flux ar ZZ4	nd all contaminants. Use of no cle						
	D			Texas Instruments and/or its licensors warrant that this design will meet the s licensors do not warrant that the desic	do not warrant the accuracy or compl specifications, will be suitable for your a n is production worthy. You should co	leteness of this specification or an application or fit for any particular mpletely validate and test your de	y information contained therein. T purpose, or will operate in an impl sign implementation to confirm th	exas Instruments and/or its licensors lementation. Texas Instruments and/o e system functionality for your applica	Number: PMP7902 Rev do not SVN Rev: Not in version cor its Drawn By: tion. Engineer: Robert Sheehan

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